



*From Nano to Micro Power Electronics
And Packaging Workshop
October the 11th and 12th, 2017
Tours, France*



PRELIMINARY PROGRAMME

Technical Committee: Stéphane BELLENGER, éolane, France – General Chairman
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Christophe SERRE, ST Microelectronics, France - Chairman
Nicolas VIVET, ST Microelectronics, France – SMA3 Programme coordinator
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Cyril BUTTAY, Ampère Laboratory, France
Jean-Luc Diot, Minapack, France
Guo-Quan LU, Virginia Tech, USA
Jürgen SCHUDERER, ABB Corporate Research, Switzerland
Sébastien JACQUES, Greman Laboratory, France

FIRST DAY PRELIMINARY CONFERENCE PROGRAMME (October the 11th, 2017)

9 h 00 Workshop package and badge distribution

9 h 30 Welcome: workshop programme presentation

9 h 50 SAM3 conference introduction: About the new assembly and packaging, by Klauss Pressel from Infineon and SAM3 project leader

10 h 40 Coffee break / Table Top Exhibition

11 h 10 Failure Analysis Session

11 h 10 Short description of the SAM3 project for IMAPS partners, by Klauss Pressel (SAM3 Project Leader), ST Microelectronics and Greman Institute
“Make the link between these new technologies & the corresponding analytical challenges”

11 h 40 Non-destructive analysis method and Predictive images

12 h 10 Table Top Exhibition visit

12 h 30 Lunch (Buffet)

13 h 30 Failure Analysis Session (Con't)

13 h 30 Defect localization in 3D System-in-Packages based on Lock-in-Thermography and GHz- Scanning Acoustic Microscopy” by Frank Altmann and Sebastian Brand from Fraunhofer Institute for Microstructure of Materials and Systems IMWS, Center for Applied Microstructural Diagnostics CAM, Halle Germany

14 h 00 Case study including defect localization method (Sector technology)

14 h 30 Sample preparation – laser (3D Micromac)

15 h 00 Coffee break / Table Top Exhibition

15 h 15 Failure Analysis Session (Con't)

15 h 15 Latest development for failure analysis – “When ions meet chemistry” by Gregory Goupil from Tescan / Orsay Physics

15 h 45 Presentation on failure analysis, from Bosh

16 h 15 End of session

SECOND DAY PRELIMINARY CONFERENCE PROGRAMME (October the 12th, 2017)

8 h 30 Workshop package and badge distribution

9 h 00 Welcome: Second day workshop programme presentation

9 h 20 Keynotes : Additive Manufacturing of Power Electronics Magnetics, by Guo-Quan Lu from VirginiaTech, USA

10 h 05 Coffee break / Table Top Exhibition

10 h 30 Session 1

10 h 30 Investigation on Cu-Sn inter-diffusion for power semi-conductor packaging by Yousra Bettahi from ST Microelectronics Tours, France

10 h 55 Hybrid silver sintering die-attach paste for multi-die packaging of mid-power solutions by Alexandre Val from ASE Europe, Bruxelles, Belgium

11 h 20 Reliability analysis of Cu-Sn intermetallic joints elaborated at low temperature by transient Liquid Phase Bonding Process, by Jean-Luc Diot, Minapack, Grenoble, France

11 h 45 Paper N°5 under definition

12 h 10 Table Top Exhibition visit

12 h 35 Lunch (Buffet)

13 h 45 Keynotes : Panel Level Packaging for Power Applications, by Rolf Aschenbrenner from IZM Fraunhofer Institute, Berlin, Germany

14 h 30 Session 2

14 h 30 Fine Pitch Solder Bumping by Printing through Dry Film Photo Resist by Gabriel Parès from the CEA-Leti, Grenoble, France

14 h 55 Paper N°8 under definition

15 h 20 Paper N°9 under definition

15 h 45 Coffee break / Table Top Exhibition

16 h 05 Session 2 (con't)

16 h 05 Processes and Packaging dedicated to Power Module for automotive application by Nicolas Meillerais from éolane Angers, France

16 h 30 Paper N°10 under definition

16 h 55 End of session

Next to the first workshop sessions of 11th of October, an exceptional event will be organized for which you need to register if you wish to attend:

- **On Wednesday, October the 11th from 16:30 a visit of famous castle near Tours town will be organized. Departure from Greman's institute at 16h30**
- **On Wednesday, October the 11th at 19h30 a dinner in a gastronomic restaurant is proposed as well**

Sponsors:



éolane

**International Microelectronics and Packaging Society – France
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E-mail : imaps.france@imapsfrance.org**

Registration Form
Final registration October the 2nd, 2017

COMPANY:

NAME:

FIRSTNAME:

ADDRESS:

TEL:

E-MAIL:

→Send back to Florence Vireton Fax : +33 (0)1 39 02 71 93

E-mail: imaps.france@imapsfrance.org

FEES (include lunch, breaks & 2-days events)

Conferences on free access on website www.imapsfrance.org after the event.

- IMAPS MEMBER 220 € HT excluding - 263.12 € TTC**
- Non IMAPS MEMBER 250 € HT - 299.00 € TTC**
- SPEAKERS/CHAIRS 180 € HT - 215.28 € TTC**
- Table Top 300 € HT - 358, 80 € TTC** (1 table, chairs, panel, conferences attendance, coffee breaks, lunch). **For foreign companies, VAT is excluded**

Do not forget to tick boxes if you want to participate

- **Visit of a typical Touraine castle (Wednesday evening)** **yes** **no**

- **Dinner after the visit (Wednesday evening)** **yes** **no**

- On line Payment and Registration available on www.france.imapseurope.org**

TRAINING AGREEMENT

INTERCONEX is recognized as approved training centre (Training agreement number 11780608378). If you would like a training agreement, check the following box . A certificate of attendance will be given during training

PAYMENT AND INTERCONEX BANK REFERENCES

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